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IECON'01

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Special Session on Software Engineering

organized and chaired by

Jim Coplien, Bell Labs, Lucent
Elke Pulvermüller, University of Karlsruhe, Germany
Andreas Speck, University of Tuebingen, Germany

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Call For Papers

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wilam@ieee.org

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f.harashima@ieee.org

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hashimoto@ics.iis.u-tokyo.ac.jp

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University of Maribor, Slovenia.
karel.jezernik@uni-mb.si

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masaki@mit.edu

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olekmali@ieee.org

The importance of software is constantly increasing. Even in the domain of industrial electronics more and more pure hardware systems are replaced or enhanced by software. Tasks formerly performed by hardware are now executed by software systems. Facing this development, the challenge is to build high-quality software. Which methods or techniques may be applied in order to assure a certain degree of software quality?

The issue of this special session is the application of software engineering approaches in an industrial hardware-oriented environment.

Topics of interest include, but are not limited to:

- procedural, object-oriented, functional programming, multi-paradigm software engineering
- patterns, frameworks and components
- approaches dealing with the feature interaction problem
- verification of software systems
- generative and component-based software engineering
- requirements engineering and domain analysis
- distributed systems and networking with respect to software engineering principles
- other topics related to the conference scope and/or of interest to the prospective conference participants.

Submission of Papers: The working language of the conference is English. Submit a full paper using the following layout: Page 1: title, authors' names, mailing address, phone, fax, and email of each author. Identify the contact author, preferred topical area, subject area and keywords. Page 2: title, authors' affiliations, 100–200 words abstract. Pages 3–8: full paper limited to 6 pages, including figures and references. Submit full papers in postscript or pdf format by e-mail to pulvermu@ipd.info.uni-karlsruhe.de.

Author's Schedule:

Deadline for Submission of Full Papers: May 01, 2001
Notification of Acceptance: June 15, 2001
Deadline for Submission of Final Manuscripts: August 15, 2001

For general information please check the conference web page:
<http://sant.bradley.edu/~iecon01/>